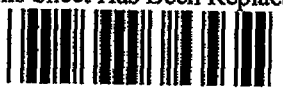
SEMICONDUCTOR DEVICE, METHOD OF MAKING THE SAME AND MOUNTING THE SAME, CIRCUIT BOARD AND FLEXIBLE SUBSTRATE WITH THE SAME MOUNTED THEREON AND METHOD OF MAKING THE SAME

ABSTRACT

A semiconductor device includes a semiconductor element, an insulating film and a wiring pattern. The insulating film has a first opening and a plurality of second openings. At least part of the semiconductor element is positioned in the first opening when the semiconductor element is disposed on the insulating film. The second openings are provided aligned around the first opening. Each of the second openings has a pair of long edges in an approximately quadrilateral shape. The long edges are positioned at right angles to the closest one of edges defining the first opening. The wiring pattern is formed on a surface of the insulating film and connected to the semiconductor element. The wiring pattern has a plurality of connection portions at its extremity. Ones of the connection portions are positioned in each of the second openings. The ones of the connection portions are disposed in a staggered fashion facing toward a center of each of the second openings from the long edges of each of the second openings.

Figure 1

This Sheet Has Been Replaced



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